



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE COMMISSIONER OF PATENTS

Appl. Serial No. : 10/790,747
Applicant : John M. Lauffer et al
Filed : 03/03/04
Art Unit : 2841
Examiner : Hoa Cao Nguyen
Docket No. : EI-2-04-002
Title : Circuitized Substrate With Signal Wire Shielding, Electrical
Assembly Utilizing Same and Method of Making
Assignee : Endicott Interconnect Technologies, Inc.

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE AFTER FINAL REJECTION

Dear Sir:

In response to the final Office Action mailed 09/06/06, please amend the above-identified application as follows. **It is urged that this Response places the application in condition for allowance and does not require further consideration and/or search by the Examiner.** Allowance is respectfully requested.

An Amendment to the Specification is on page 2 of this Response.

There are no further Amendments to the Claims over those previously presented. The Listing of Claims remaining herein begins on page 3 of this Response.

No Amendment to the Drawings is necessary.

Remarks/Arguments begin on page 8 of this Response.

DO NOT ENTER